

Amendments to the Claims:

1. (currently amended) A curable composition that is controllably curable by microwave energy comprising:
 - a) at least one heat curable resin component;
 - b) microwave absorbable particles having a Curie temperature at or above the cure temperature of said heat curable resin component and below the degradation temperature of said heat curable resin component and said particles being present in an amount of about greater than 10% by weight of said composition; and
 - c) at least one curing agent for said heat curable resin component.
2. (original) A composition according to claim 1 wherein said microwave absorbable particles are in an amount sufficient to uniformly cure said composition.
3. (currently amended) A composition according to claim 1 wherein said microwave absorbable particles are in an amount ~~of at least about greater than~~ 10% to about 40% by weight of said composition.
4. (original) A composition according to claim 1 wherein said microwave absorbable particles are selected so that the Curie temperature of said particles is higher than the curing temperature of said heat curable resin component.
5. (original) A composition according to claim 1 wherein said microwave absorbable particles comprise a ferromagnetic compound.
6. (original) A composition according to claim 1 wherein said microwave absorbable particles are selected from the group consisting of ferrite, amorphous carbon, carbon black, graphite and combinations thereof.
7. (currently amended) A ~~composition~~ composition according to claim 1 wherein said curable resin component is selected from the group consisting of acrylics, elastomeric synthetic

rubbers, epoxies, polyesters, polyurethanes, polybutadienes, cyanate esters, bismoleimides, polyimides, phenolics, silicones, acrylic silicones, epoxy silicones and copolymers and combinations thereof.

8. (original) A composition according to claim 1 wherein said heat curable resin is an elastomeric composition.
9. (original) A composition according to claim 1 wherein said heat curable resin is a heat curable silicone.
10. (original) A composition according to claim 1 wherein said curing agent is an addition curing catalyst.
11. (original) A composition according to claim 1 wherein said curing agent is selected from the group consisting of an amine-containing compound, an azo compound and a peroxide curing agent.
12. (currently amended) A composition according to claim 11 wherein said peroxide curing agent is selected from the group consisting of ~~cumene hydroperoxide~~ cumene hydroperoxide, methyl ethyl ketone hydroperoxide, percarbonates, diacyl peroxides, per-esters, per-acids and combinations thereof.
13. (original) The composition accordingly to claim 1, further including a material selected from the group consisting of inhibitors, viscosity modifying agents, catalysts, coloring agents, fluorescent agents, and combinations thereof.
14. (original) The compositions according to claim 13 wherein said viscosity modifying agent is selected from the group consisting of fumed silica, precipitated silica, titanium dioxide, lithopone, zinc oxide, zirconium silicate, silica aerogel, iron oxide, diatomaceous earth, calcium carbonate, silazane treated silicas, glass fibers, magnesium oxide, chomic oxide, zirconium

oxide, aluminum oxide, alpha quartz, calcined clay, carbon, graphite, cork, cotton, synthetic fibers and combinations thereof.

15. (original) The composition according to claim 13 wherein said viscosity modifying agent is in an amount from about 0.1 % to about 60 % of the total composition.

16. (original) The compositions according to claim 13 wherein said catalyst comprises a platinum catalyst complex.

17. (original) The compositions according to claim 13 wherein said catalyst is an amount from about 0.02 % to about 10.00 % of the total composition.

18. (original) The compositions according to claim 13 wherein said inhibitor is selected from the group consisting of methylvinyl cyclotetrasiloxane, trialkylcyanurates, alkylmaleates and combinations thereof.

19. (original) The compositions according to claim 13 wherein said inhibitor is selected from the group consisting of hexamethyldisilizane, amines, α - hydroxyacetylene and combinations thereof.

20. (original) The composition according to claim 1 wherein said heat curable resin component is selected from the group consisting of monomers, oligomers, polymers and combinations thereof.

21. (currently amended) A method of controllably curing a composition comprising:

a) selecting microwave absorbable particles having a Curie temperature at or above a cure temperature of a heat curable resin component and below a degradation temperature of said heat curable resin component a desired Curie temperature;

b) combining said microwave absorbable particles with a curing agent and a heat curable resin component ~~which has a curing temperature lower than said Curie temperature~~, said resin

being substantially transparent to microwave energy such that and said particles being present in an amount of about greater than 10% by weight of said composition; and

c) applying a sufficient amount and wavelength of microwave energy to said composition to achieve the desired heating temperature.

22. (original) A method according to claim 21 wherein said microwave absorbable particles are dispersed in an amount sufficient to cure said composition.

23. (original) A method according to claim 21 wherein said composition is cured.

24. (original) A method according to claim 21 wherein said microwave absorbable particles are dispersed only within selected portions of said heat curable resin component such that only said selected portions melt when said compositions are exposed to microwave energy.

25. (original) A method according to claim 21 wherein the microwave absorbable particle comprises a ferromagnetic compound.

26. (original) A method according to claim 21 wherein the microwave absorbable particle are selected from the group consisting of ferrite, amorphous carbon, carbon black, graphite and combinations thereof.

27. (currently amended) A method according to claim 21 wherein said heat curable resin component is selected from the group consisting of acrylics, epoxies, polyesters, polyurethanes, polybutadienes, cyanate esters, ~~bismoleimides~~-bismaleimides, polyimides, phenolics, silicones and combinations thereof.

28. (original) A method according to claim 21 wherein said heat curable resin component is selected from the group consisting of monomers, oligomers, polymers and combinations thereof.

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29. (original) A method according to claim 21 wherein said microwave energy is in a range from about 10KHz to about 100 GHz.

30. (original) A method according to claim 21 further comprising the step of applying said heat curable resin component between two members to be joined and wherein the application of microwave energy melts said composition and joins said members.